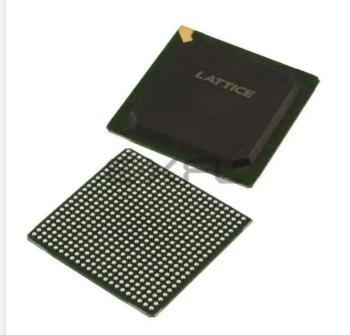
Lattice Semiconductor Corporation - <u>LFEC20E-4F484I Datasheet</u>



Welcome to **E-XFL.COM**

Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	19700
Total RAM Bits	434176
Number of I/O	360
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec20e-4f484i

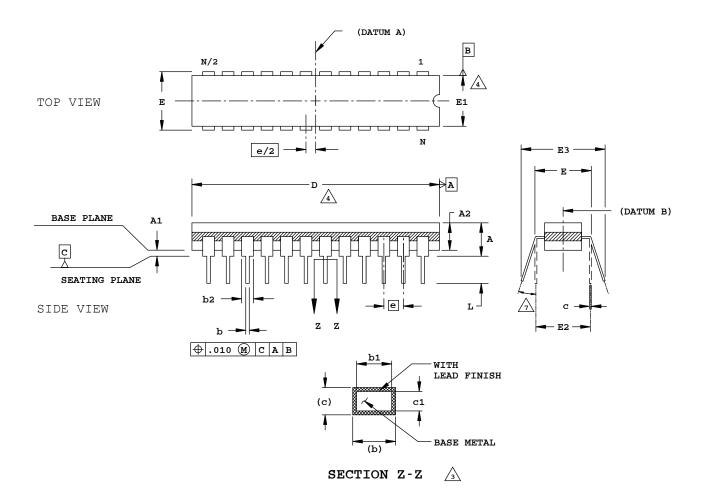
Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



24-Pin (300-Mil) CERDIP

Dimensions in Inches



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN INCHES.



MEASUREMENTS TO BE TAKEN AT A MINIMUM OF .060 INCHES FROM THE LEAD TIP.



DIMENSIONS D AND E1 INCLUDE ALLOWANCE FOR GLASS OVERRUN AND MENISCUS, AND LID TO BASE MISMATCH.

- 5. DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-003.
- 6. E3 IS TO BE MEASURED AT THE LEAD TIPS.



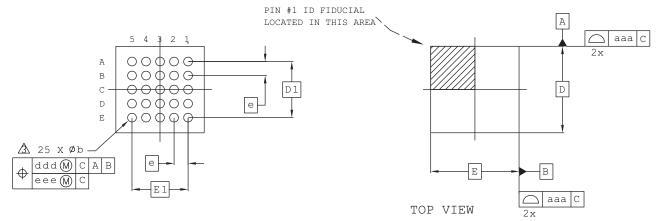
ALLOWED LEAD TIP POSITION RANGE.

S Y M B	INCHES		
o L	MIN.	NOM.	MAX.
A	-	-	.200
A1	.015	-	-
A 2	.140	-	.175
b	.015		.023
b1	.015	.018	.021
b2	.045	-	.065
С	.008	-	.014
c1	.008	.010	.012
D	1.242	1.250	1.270
E	.308		.325
E1	.280	.288	.296
E2	. 3	00 REF	,
E 3	.325	-	.410
е	.100 BSC		
L	.125	-	.200
N	24		

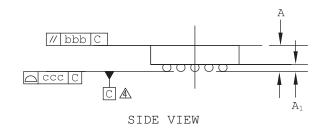


25-Ball WLCS Package (0.40 mm Pitch)

Dimensions in Millimeters



BOTTOM VIEW



Notes:

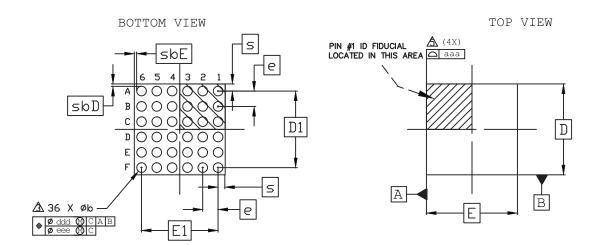
- 1 ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2 ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- A PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

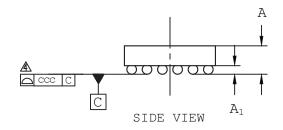
REF.	Min.	Nom.	Max.
А	0.535	0.575	0.615
A1	0.170	0.200	0.230
b	0.220	0.250	0.280
D	2	.492 BS	SC
E	2	.546 BS	SC
D1	1	.60 BSC	
E1	1.60 BSC		
е	0.40 BSC		
aaa	0.025		
bbb	0.060		
ccc	0.015		
ddd	0.150		
eee	0	.050	



36-Ball WLCS Package Option 1: iCE40 Ultra

Dimensions in Millimeters





NOTES:

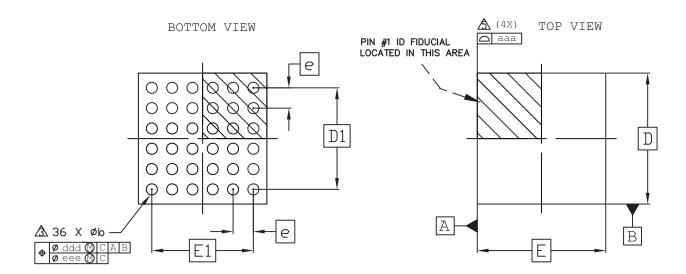
- 1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- \triangle DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM $\boxed{\text{C}}$.
- \triangle PRIMARY DATUM $\mathbb C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
- $\ensuremath{\Delta}$ bilateral tolerance zone is applied to each side of the package body.

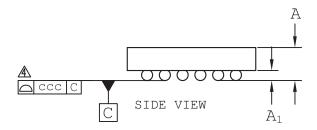
REF.	Min.	Nom.	Max.
А	0.413	0.452	0.491
A1	0.122	0.152	0.182
b	0.188	0.218	0.248
D		2.078 BS	С
E	:	2.078 BS	С
D1		1.75 BSC	:
E1		1.75 BSC	!
е	(0.35 BSC	!
s	0.157	0.164	0.172
sbD	0.051	0.055	0.056
sbE	0.051	0.055	0.056
aaa	0.030		
ccc	0.030		
ddd	0.015		
eee	0.050		



36-Ball WLCS Package Option 3: LIFMD™

Dimensions in Millimeters





NOTES:

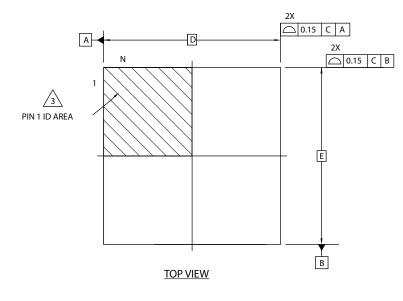
- 1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- \triangle PRIMARY DATUM $\boxed{\text{C}}$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
- \triangle BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

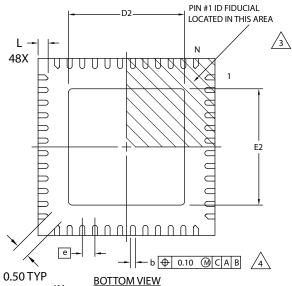
REF.	Min.	Nom.	Max.
А	-	-	0.600
A1	0.113	-	-
b	0.188	0.218	0.248
D	:	2.535 BS	С
E		2.583 BS	С
D1	2.00 BSC		
E1	2.00 BSC		
е	0.40 BSC		
aaa	0.030		
ccc	0.050		
ddd	0.050		
eee		0.015	

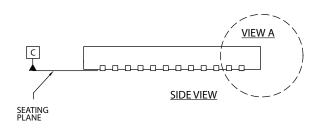


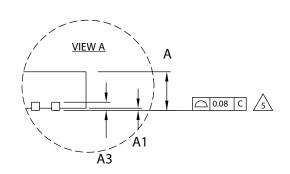
48-Pin QFN Package Option 1

Dimensions in Millimeters









NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\underline{ \begin{tabular}{ll} λ & EXACT SHAPE AND SIZE OF THIS \\ FEATURE IS OPTIONAL. \end{tabular}$

DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

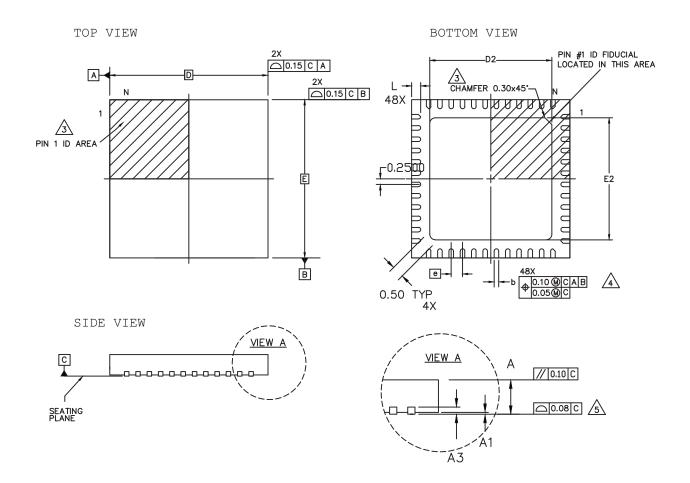
APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
А	0.80	0.90	1.00
A1	0.00	0.02	0.05
А3		0.2 REF	
D	7.0 BSC		
D2	3.00	-	5.80
E	7.0 BSC		
E2	3.00	-	5.80
b	0.18	0.24	0.30
е	0.50 BSC		
L	0.30	0.40	0.50



48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra, iCE40 UltraPlus, MachXO2

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

<u> 3</u>

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

4

DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

/5\

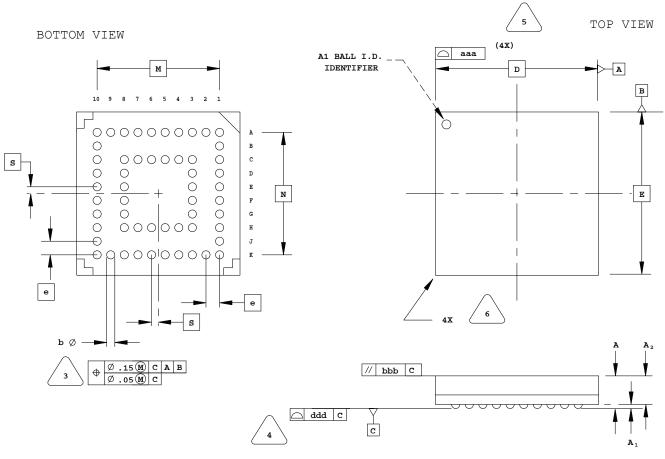
APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
А	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3		0.2 REF	
D		7.0 BSC	
D2	5.30	5.40	5.50
E	7.0 BSC		
E2	5.30	5.40	5.50
b	0.15	0.20	0.25
е	0.50 BSC		
L	0.35	0.40	0.45



56-Ball csBGA Package

Dimensions in Millimeters



SIDE VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\[\]$



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

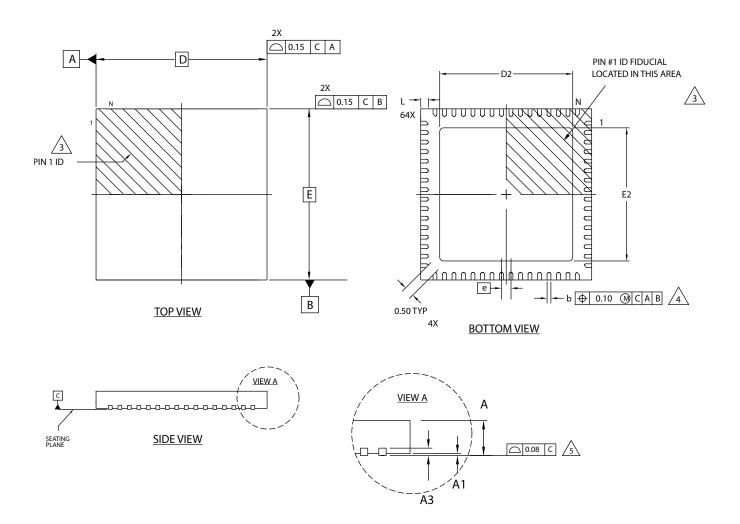


SYMBOL	MIN.	NOM.	MAX.
A	1.10	1.23	1.35
A1	0.15	-	-
A2	-	-	1.10
D/E	6.00 BSC		
M/N	4	.50 BSC	
s	0	25 BSC	
b	0.25	0.30	0.35
е	0	.50 BSC	
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08



64-Pin QFNS Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

DIMENSION b APPLIES TO PLATED
TERMINAL AND IS MEASURED BETWEEN
0.15 AND 0.30 mm FROM TERMINAL TIP.

___________________________________APPLIES TO EXPOSED PORTION OF TERMINALS.

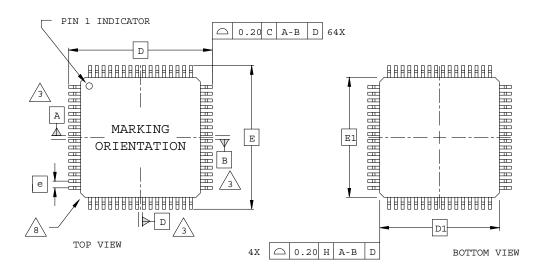
SYMBOL	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
А3		0.2 REF	
D	9.0 BSC		
D2	5.00	_	7.50
E	9.0 BSC		
E2	5.00	-	7.50
b	0.18	0.24	0.30
е	0.50 BSC		
L	0.30	0.40	0.50

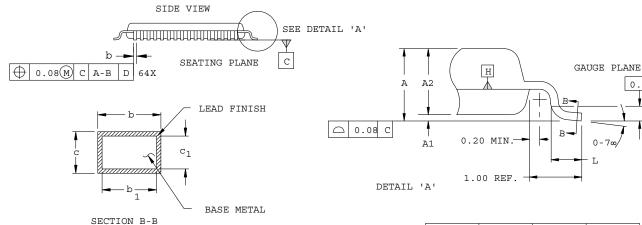
0.25



64-Pin TQFP Package

Dimensions in Millimeters





NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- ALL DIMENSIONS ARE IN MILLIMETERS.

DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B: THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

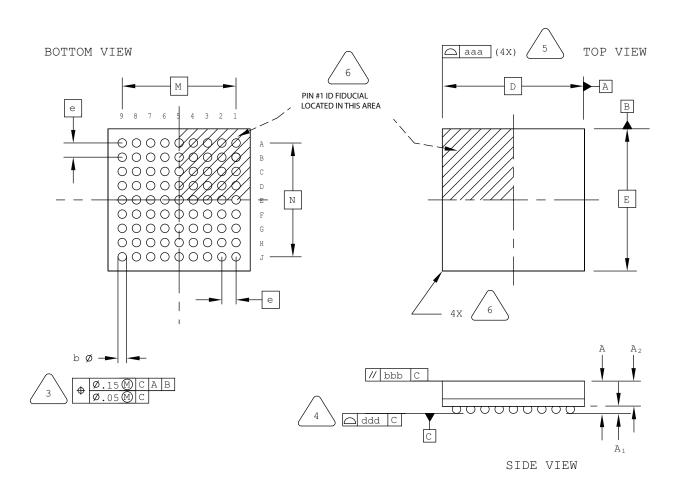
/8\ EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D		12.00 BSC	
D1		10.00 BSC	
E		12.00 BSC	
E1	10.00 BSC		
L	0.45	0.60	0.75
N	64		
е	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
С	0.09	-	0.20
c1	0.09	-	0.16



81-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

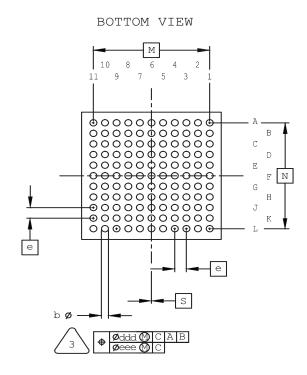


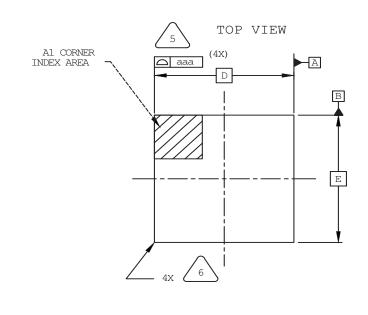
SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.00
A1	0.10	_	-
A2	1	-	0.90
D/E	4.00 BSC		
M/N	3	.20 BSC	
b	0.20	0.25	0.30
е	0.40 BSC		
aaa	_	_	0.10
bbb	-	_	0.10
ddd	-	_	0.10

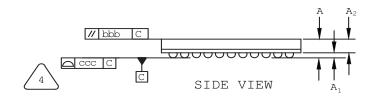


121-Ball csfBGA Package

Dimensions in Millimeters







NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM $\overline{\mathbb{C}}$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

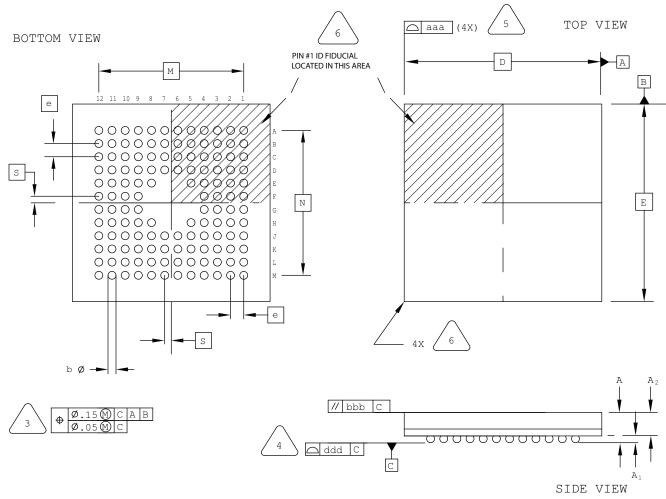


SYMBOL	MIN.	NOM.	MAX.
А	_	_	1.00
A1	0.15	0.24	-
A2	_	0.66	ı
D/E		6.00 BSC	
M/N	5.00 BSC		
S		0.00 BSC	
b	0.25	0.30	0.35
е	0.50 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee		0.05	



132-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

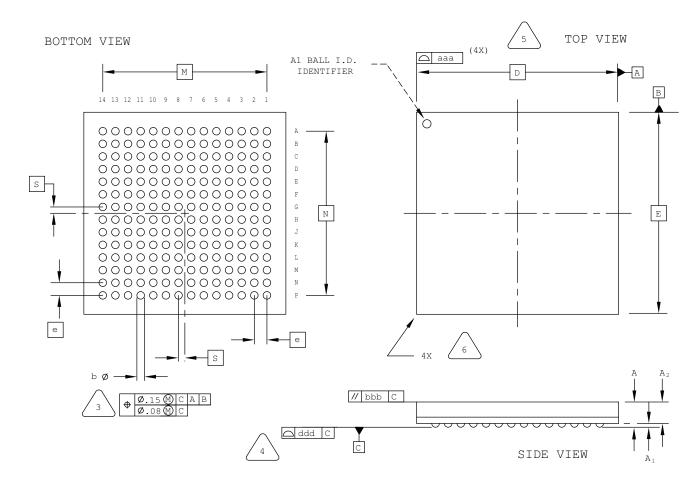


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.00
A1	0.10	-	ı
A2	-	_	0.90
D/E	6.00 BSC		
M/N	4.40 BSC		
S	0.20 BSC		
b	0.20	0.25	0.30
е	0.40 BSC		
aaa	0.10		0.10
bbb	_	-	0.10
ddd	_	_	0.08



196-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

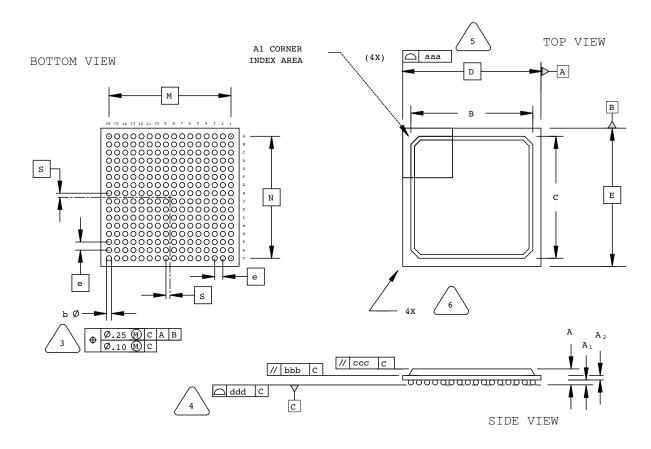


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.00
A1	0.15	_	_
A2	_	_	0.85
D/E	8.00 BSC		
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
е	0.50 BSC		
aaa			0.10
bbb	_	_	0.10
ddd	_	_	0.08



256-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

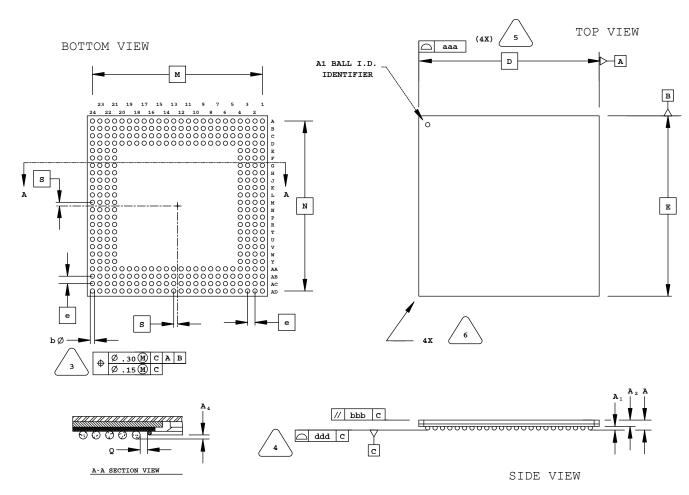


			-
SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.70	2.10
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
в/с	14.80	15.30	15.80
D/E	17.00 BSC		
M/N	15.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	_	0.25
ccc	-	_	0.35
ddd	-	_	0.20



320-Ball SBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES
 PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

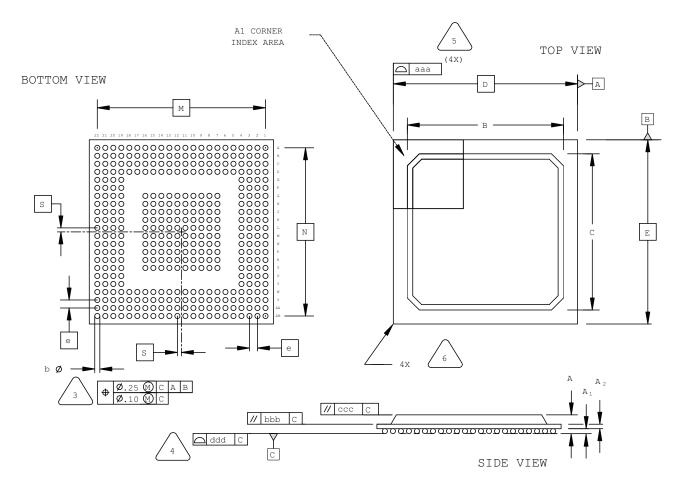


SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.50	0.65	0.80
A2	0.80	0.90	1.00
D/E	3:	1.00 BSC	
M/N	29.21 BSC		
s	0.635 BSC		
b	0.60	0.75	0.90
е	1.27 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20



388-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

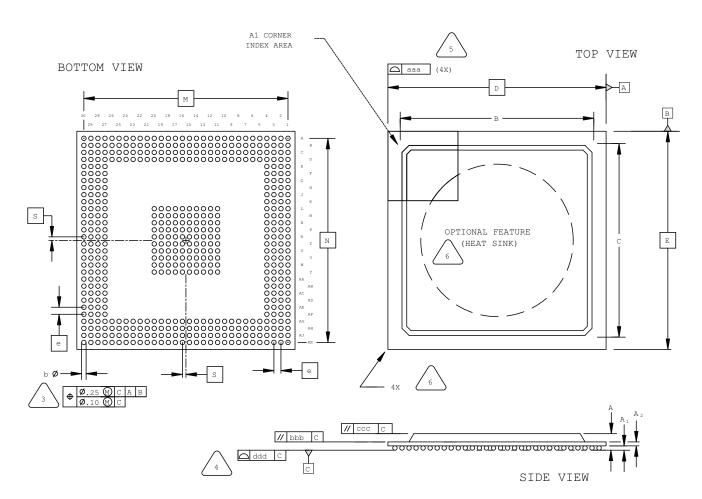


SYMBOL	MIN.	NOM.	MAX.
А	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	19.30	19.80	20.30
D/E	23.00 BSC		
M/N	21.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa			0.20
bbb			0.25
ccc	-	-	0.35
ddd	-	-	0.20



516-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

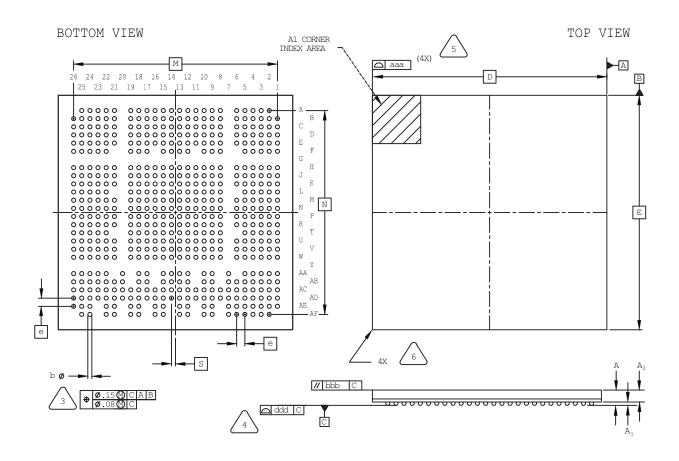


SYMBOL	MIN.	NOM.	MAX.
А	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	25.80	27.55	29.30
D/E	31.00 BSC		
M/N	29.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	0.20		0.20
bbb			0.25
ccc	-	-	0.35
ddd	-	-	0.20



554-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\sqrt{3}$

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\boxed{\mathbb{C}}$



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

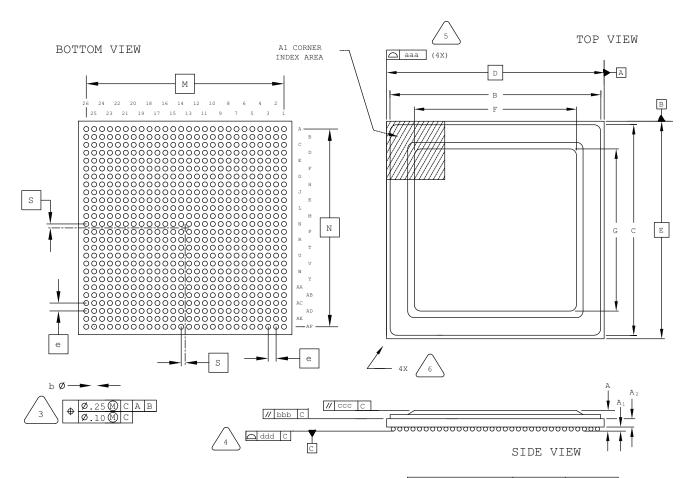


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.76
A1	0.25	0.30	0.35
A2	0.80	-	-
D/E	23.0 BSC		
M/N	20.0 BSC		
S	0.40 BSC		
b	0.35	0.40	0.45
е	0.80 BSC		
aaa	_	_	0.15
bbb	-	_	0.20
ddd	_	_	0.12



676-Ball fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

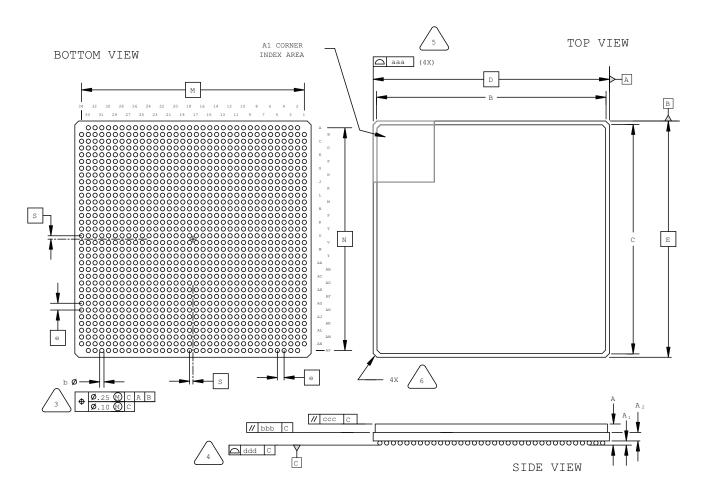


SYMBOL	MIN.	NOM.	MAX.
A	2.55	2.90	3.25
A1	0.40	0.50	0.60
A2	1	1.20 REF	
B/C	26.55	26.60	26.65
D/E	2	7.00 BSC	
F/G	18.55	18.60	18.65
M/N	25.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	_	_	0.20



1152-Ball Ceramic fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

 DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

3

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C





BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.
А	4.00	4.60	5.20
A1	0.30	0.50	0.70
A2	1	.40 REF	
B/C	33.10	34.00	34.90
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	0.25		0.25
ccc	-	-	0.35
ddd	-	_	0.20